# mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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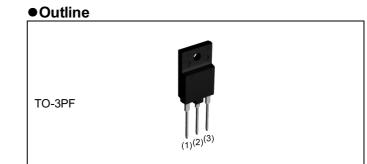
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



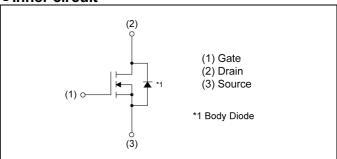


Nch 600V 35A Power MOSFET

V <sub>DSS</sub>	600V
R <sub>DS(on)</sub> (Max.)	0.102Ω
I <sub>D</sub>	±35A
P <sub>D</sub>	102W



### Inner circuit



## Packaging specifications

	Packing	Tube
-	Reel size (mm)	-
	Tape width (mm)	-
Туре	Basic ordering unit (pcs)	360
	Taping code	C8
	Marking	R6035KNZ

## • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

	4			
Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	600	V
Continuous drain current $(T_c = 2)$	5°C)	۱ <sub>D</sub> *1	±35	А
Pulsed drain current	I <sub>DP</sub> *2	±105	А	
Cata Cauraa valtara	static	M	±20	V
Gate - Source voltage	AC(f>1Hz)	$V_{GSS}$	±30	V
Avalanche current, single pulse		I <sub>AS</sub>	6.6	А
Avalanche energy, single pulse		E <sub>AS</sub> *3	796	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P <sub>D</sub>	102	W	
Junction temperature	Tj	150	°C	
Operating junction and storage te	T <sub>stg</sub>	-55 to +150	°C	

1) Low on-resistance.

3) Parallel use is easy.

2) Ultra fast switching speed.

4) Pb-free lead plating ; RoHS compliant

Features

Application

Switching

### •Thermal resistance

Deremeter	Cumphia	Values			Lincit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}^{*4}$	-	-	1.2	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	40	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## •Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Sumbol	Conditions	Values			- Unit	
Parameter	Symbol Conditions -		Min.	Тур.	Max.	UTIIL	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		600	-	-	V	
		V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V					
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μA	
		$T_j = 125^{\circ}C$	-	-	1000		
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	3	-	5	V	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 18.1A					
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	$T_j = 25^{\circ}C$	-	0.092	0.102	Ω	
		$T_j = 125^{\circ}C$	-	0.200	-		
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	1.0	-	Ω	



## •Electrical characteristics (T<sub>a</sub> = 25°C)

Devenuetor	C: make al	Conditions	Values			Linit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Admittance	Y <sub>fs</sub>   <sup>*5</sup> V <sub>DS</sub> = 10V, I <sub>D</sub> = 17.5A		11	22	-	S	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	3000	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	2300	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	80	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 300$ V, $V_{GS}$ = 10V	-	45	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 17.5A	-	150	-	-	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ≃ 17.4Ω	-	90	-	ns	
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	95	-		

## • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Cumph of	Conditions	Values			L locit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	$V_{DD} \simeq 300V$	-	72	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 35A	-	20	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	30	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 300$ V, I <sub>D</sub> = 35A	-	6.6	-	V

\*1 Limited only by maximum channel temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L $\doteqdot$ 50mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>j</sub>=25°C

\*4 T<sub>C</sub>=25°C

\*5 Pulsed

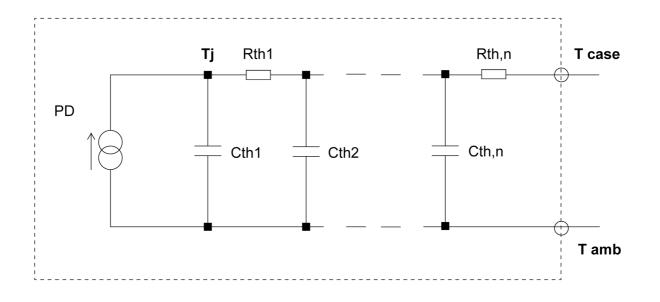


## •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Sumbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Continuous forward current	۱ <sub>S</sub> *1	T - 25°0	-	-	35	А	
Pulse forward current	ا <sub>SP</sub> *2	T <sub>C</sub> = 25°C	-	-	105	А	
Forward voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 35A	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5		-	605	-	ns	
Reverse recovery charge	$Q_{rr}^{*5}$ I <sub>S</sub> = 35A	I <sub>S</sub> = 35A di/dt = 100A/µs	-	14.5	-	μC	
Peak reverse recovery current	۲ <sub>rrm</sub> *5		-	45	-	А	

## • Typical transient thermal characteristics

Symbol	Value	Unit	Symbol	Value	Unit
R <sub>th1</sub>	0.0683		C <sub>th1</sub>	0.00697	
R <sub>th2</sub>	0.402	K/W	C <sub>th2</sub>	0.0677	Ws/K
R <sub>th3</sub>	1.22		C <sub>th3</sub>	1.12	





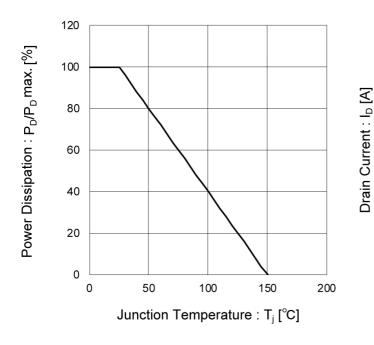


Fig.1 Power Dissipation Derating Curve

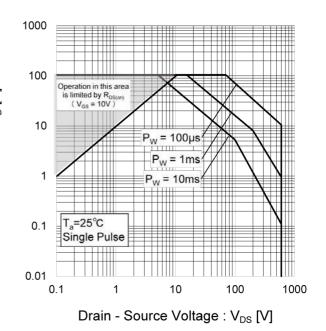
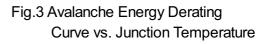
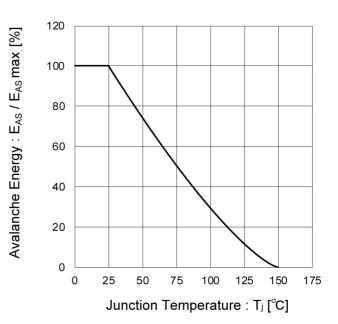


Fig.2 Maximum Safe Operating Area







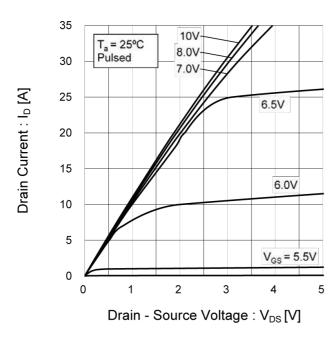
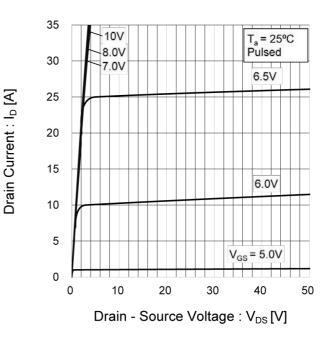
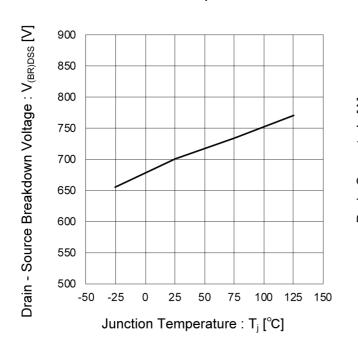


Fig.4 Typical Output Characteristics(I)

Fig.5 Typical Output Characteristics(II)







#### Fig.6 Breakdown Voltage vs. **Junction Temperature**

Fig.7 Typical Transfer Characteristics

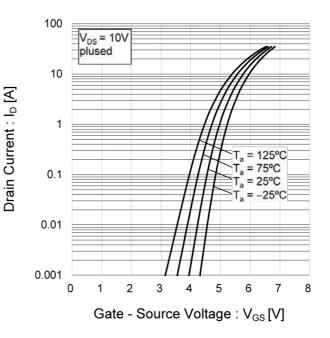
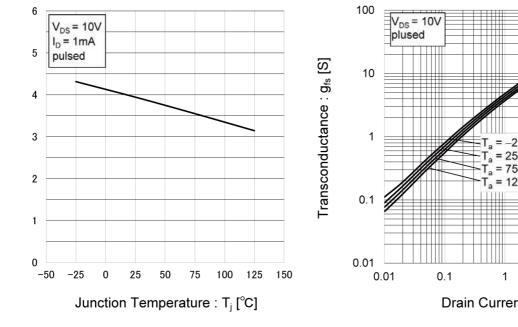
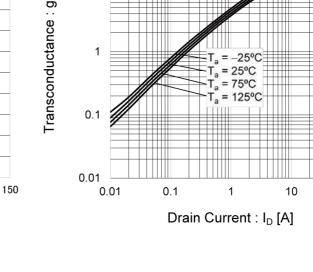


Fig.8 Gate Threshold Voltage vs. **Junction Temperature** 





## Fig.9 Forward Transfer Admittance vs. **Drain Current**





100

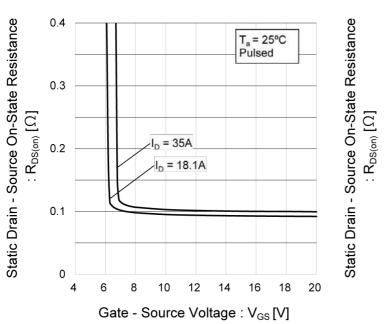
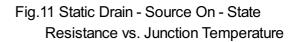


Fig.10 Static Drain - Source On - State

Resistance vs. Gate Source Voltage



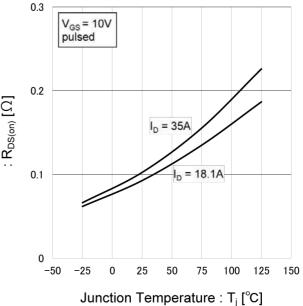
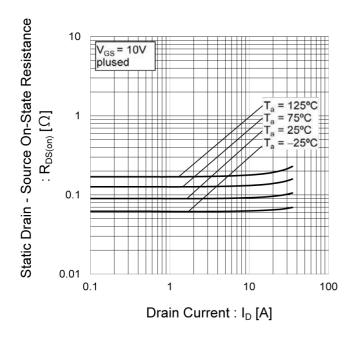


Fig.12 Static Drain - Source On - State Resistance vs. Drain Current(I)





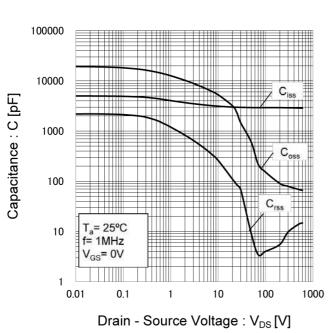
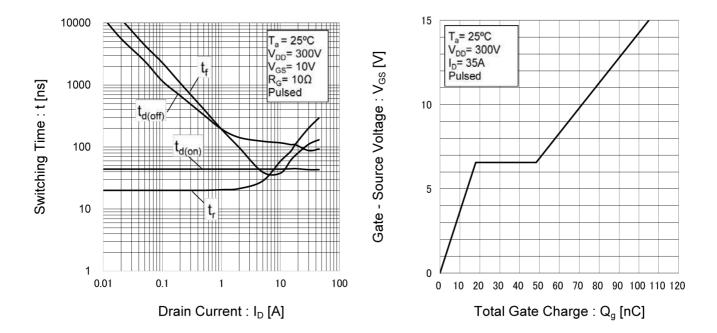


Fig.13 Typical Capacitance vs. Drain - Source Voltage

#### Fig.14 Switching Characteristics

## Fig.15 Dynamic Input Characteristics





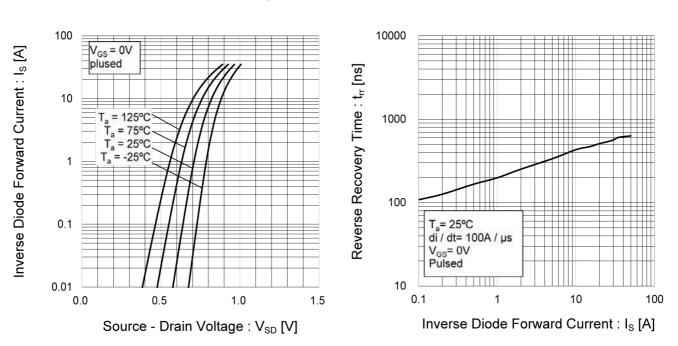
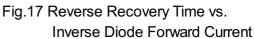


Fig.16 Inverse Diode Forward Current vs. Source - Drain Voltage





#### Measurement circuits

#### Fig.1-1 Switching Time Measurement Circuit

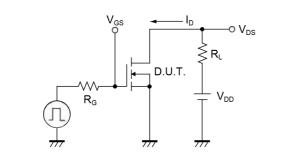


Fig.2-1 Gate Charge Measurement Circuit

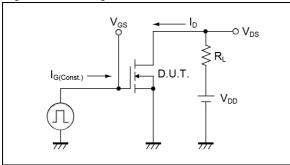


Fig.3-1 Avalanche Measurement Circuit

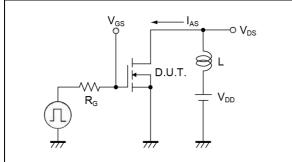


Fig.4-1 dv/dt Measurement Circuit

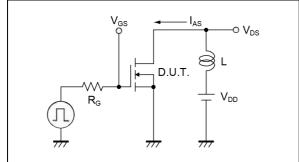
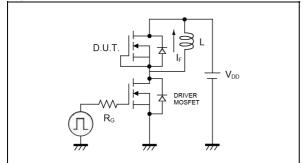
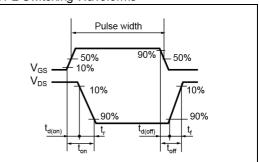


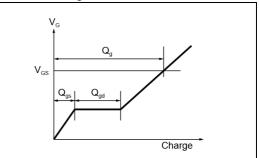
Fig.5-1 dv/dt Measurement Circuit



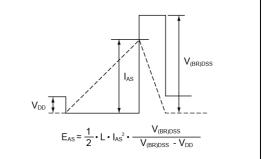
#### Fig.1-2 Switching Waveforms



#### Fig.2-2 Gate Charge Waveform



#### Fig.3-2 Avalanche Waveform



#### Fig.4-2 dv/dt Waveform

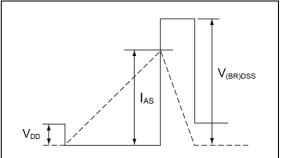
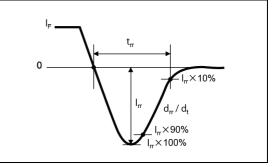
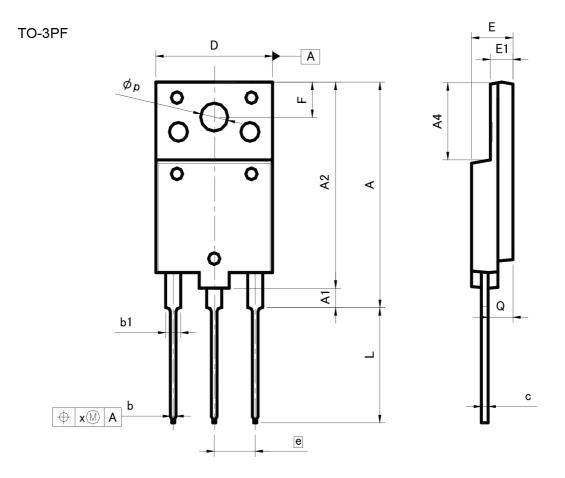


Fig.5-2 dv/dt Waveform





## Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	26.30	26.70	1.035	1.051
A1	2.30	2.70	0.091	0.106
A2	26.30	26.70	1.035	1.051
A4	9.80	10.20	0.386	0.402
b	0.65	0.95	0.026	0.037
b1	1.80	2.20	0.071	0.087
с	0.80	1.10	0.031	0.043
D	15.30	15.70	0.602	0.618
E	5.30	5.70	0.209	0.224
е	5.4	45	0.215	
E1	2.80	3.20	0.110	0.126
F	4.30	4.70	0.169	0.185
L	14.60	15.00	0.575	0.591
р	3.40	3.80	0.134	0.150
Q	3.10	3.50	0.122	0.138
x		0.50	4	0.020

Dimension in mm/inches



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  - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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## R6035KNZ - Web Page

**Distribution Inventory** 

Part Number	R6035KNZ
Package	TO-3PF
Unit Quantity	360
Minimum Package Quantity	360
Packing Type	Bulk
Constitution Materials List	inquiry
RoHS	Yes